

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SPECIFICATION

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL05C151JB5NNNC

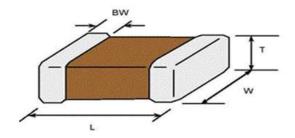
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 150 pF, 50V, ±5%, C0G, 0402

A. Samsung Part Number

<u>CL</u> <u>05</u> <u>C</u> <u>151</u> <u>J</u> <u>B</u> <u>5</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor				
2	Size	0402 (inch code)	L: 1.00 ± 0.05 mm	W: 0.50 ± 0.05 mm		
	5	000		N.E.		
3	Dielectric	C0G	8 Inner electrode	Ni		
4	Capacitance	150 pF	Termination	Cu		
⑤	Capacitance	±5 %	Plating	Sn 100% (Pb Free)		
	tolerance		Product	Normal		
6	Rated Voltage	50 V	⑩ Special	Reserved for future use		
7	Thickness	$0.50 \pm 0.05 \text{ mm}$	① Packaging	Cardboard Type, 7" reel		

B. Structure and dimension



Samsung P/N	Dimension(mm)				
(Lead Free)	L	W	Т	BW	
CL05C151JB5NNNC	1.00±0.05	0.50±0.05	0.50±0.05	0.25±0.10	

C. Samsung Reliability Test and Judgement condition

Performance	Test condition			
Within specified tolerance	1Mb±10% 0.5~5Vrms			
1,000 min				
10,000Mohm or 500Mohm· <i>µ</i> F	Rated Voltage 60~120 sec.			
Whichever is smaller				
No abnormal exterior appearance	Microscope (×10)			
No dielectric breakdown or	300% of the rated voltage			
mechanical breakdown				
COG				
(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)				
No peeling shall be occur on the	500g·F, for 10±1 sec.			
terminal electrode				
Capacitance change :	Bending to the limit (1mm)			
within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.			
More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
is to be soldered newly	245±5℃, 3±0.3sec.			
	(preheating : 80~120 ℃ for 10~30sec.)			
Capacitance change :	Solder pot : 270±5℃, 10±1sec.			
within ±2.5% or ±0.25pF whichever is larger				
Tan δ, IR : initial spec.				
Capacitance change :	Amplitude : 1.5mm			
within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)			
Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)			
Capacitance change :	With rated voltage			
within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs			
Q: 200 min				
IR : 500Mohm or 25Mohm $\cdot \mu$ F				
Whichever is smaller				
Capacitance change :	With 200% of the rated voltage			
within ±3% or ±0.3pF whichever is larger	Max. operating temperature			
Q: 350 min	1000+48/-0hrs			
IR : 1,000Mohm or 50Mohm $\cdot \mu$ F				
Whichever is smaller				
Capacitance change :	1 cycle condition			
within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature → 25°C			
Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$			
	5 cycle test			
	Within specified tolerance 1,000 min 10,000Mohm or 500Mohm·μF Whichever is smaller No abnormal exterior appearance No dielectric breakdown or mechanical breakdown COG (From -55°C to 125°C, Capacitance change s No peeling shall be occur on the terminal electrode Capacitance change : within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface is to be soldered newly Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec. Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec. Capacitance change : within ±7.5% or ±0.75pF whichever is larger Tan δ, IR : sinitial spec. Capacitance change : within ±7.5% or ±0.75pF whichever is larger Q: 200 min IR : 500Mohm or 25Mohm · μF Whichever is smaller Capacitance change : within ±3% or ±0.3pF whichever is larger Q: 350 min IR : 1,000Mohm or 50Mohm · μF Whichever is smaller Capacitance change : within ±2.5% or ±0.25pF whichever is larger			

^{*} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

- Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- 6 Any other applications with the same as or similar complexity or reliability to the applications set forth above.